

L Number	Hits	Search Text	DB	Time stamp
24	587	((chip or die) and ((substrate or board) with bismaleimide))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 18:50
25	204	((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:06
26	93	((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)) and (cure or curing)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 18:53
27	97	((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)) and ((b adj stage) or cure or curing)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 18:43
28	116	((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)) and ((b adj stage) or cure or curing or cured)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 18:43
29	12	(chip or die) and ((solder adj mask) with bismaleimide)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 18:45
30	4	((chip or die) and ((solder adj mask) with bismaleimide)) and (@ad<20000118)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 18:54
31	175	(chip or die) and ((solder adj mask) with adhesive)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:05
32	47	((chip or die) and ((solder adj mask) with adhesive)) and (adhesive with (cure or curing or (b adj stage)))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:17
33	17	((chip or die) and ((solder adj mask) with adhesive)) and (adhesive with (cure or curing or (b adj stage))) and (@ad<20000118)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:23
35	2678	(chip or die) with ((polyimide or mask) and adhesive)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:06
36	930	(chip or die) with (mask and adhesive)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:35
37	371	((chip or die) with (mask and adhesive)) and (@ad<20000118)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:07
38	11	((chip or die) with (mask and adhesive)) and (@ad<20000118)) and (((partial near (cure or curing)) or (b adj stage)))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/07 19:36

39	92	((chip or die) with (mask and adhesive)) and ((chip or die) and ((solder adj mask) with adhesive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:23
40	22	((((chip or die) with (mask and adhesive)) and ((chip or die) and ((solder adj mask) with adhesive))) and (@ad<20000118))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:36
41	54	5336931.URPN.	USPAT	2004/06/07 19:34
42	11197	(chip or die) and mask and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:35
43	502	((chip or die) and mask and adhesive) and (((partial near (cure or curing)) or (b adj stage)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:36
44	265	((((chip or die) and mask and adhesive) and (((partial near (cure or curing)) or (b adj stage)))) and (@ad<20000118))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:37
45	181	(((chip or die) and mask and adhesive) and (((partial near (cure or curing)) or (b adj stage)))) and (@ad<20000118)) and (outgass or outgassing or gas or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:54
46	84	((((chip or die) and mask and adhesive) and (((partial near (cure or curing)) or (b adj stage)))) and (@ad<20000118)) not (((((chip or die) and mask and adhesive) and (((partial near (cure or curing)) or (b adj stage)))) and (@ad<20000118)) and (outgass or outgassing or gas or voids))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:54